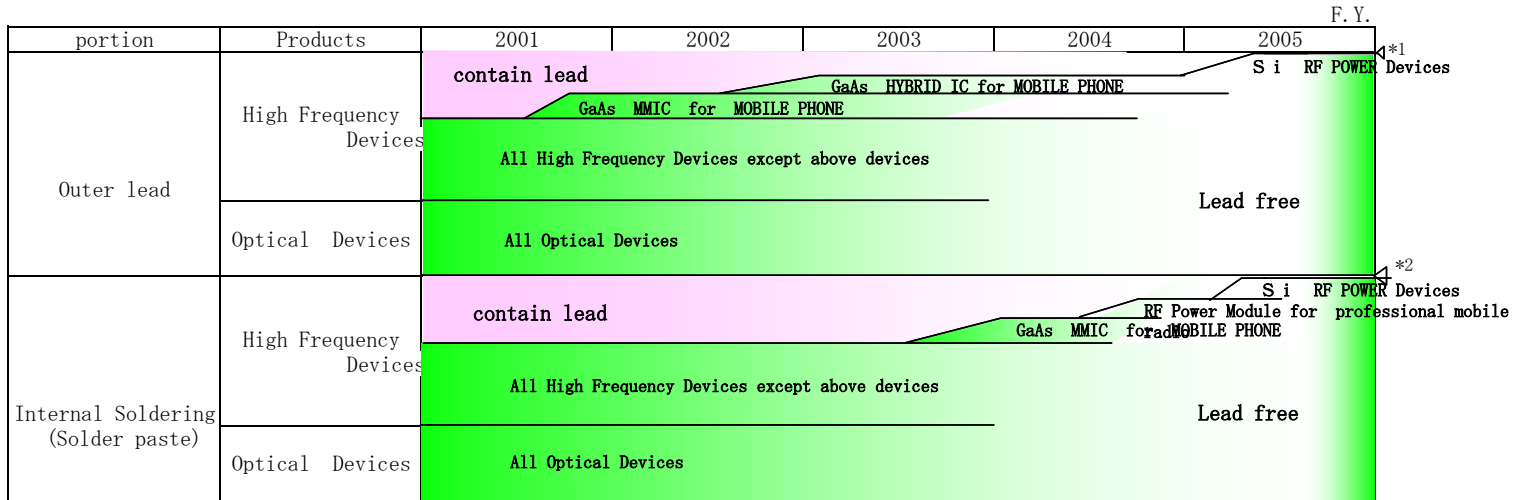


**Lead free roadmap**  
for High Frequency & Optical Devices



\*1: GaAs Hybrid IC for Mobile phone with Curent package:  
Mitsubishi has a prospect technically for Pb-free product realization. Please inquire marketing division for detail information.

\*2: Bonding solder ( bonding Substrate and Heat sink fin) used for RF power module for professional mobile radio:  
Special solder is being used. Pb-free solder/process for the bonding is under development. Please inquire marketing division for detail information.